



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

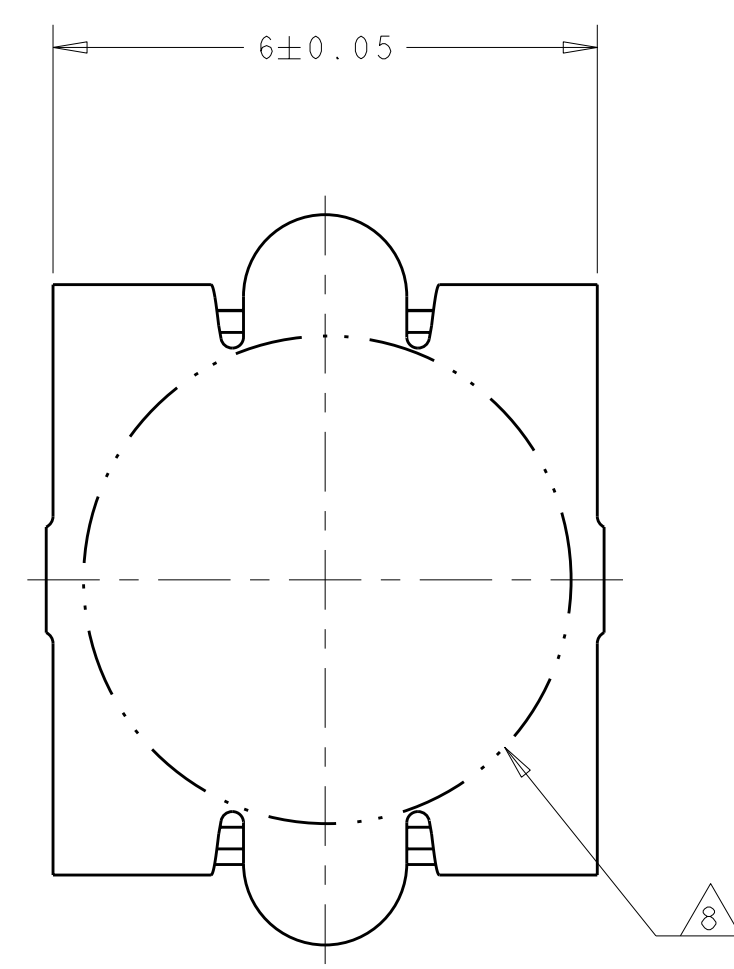
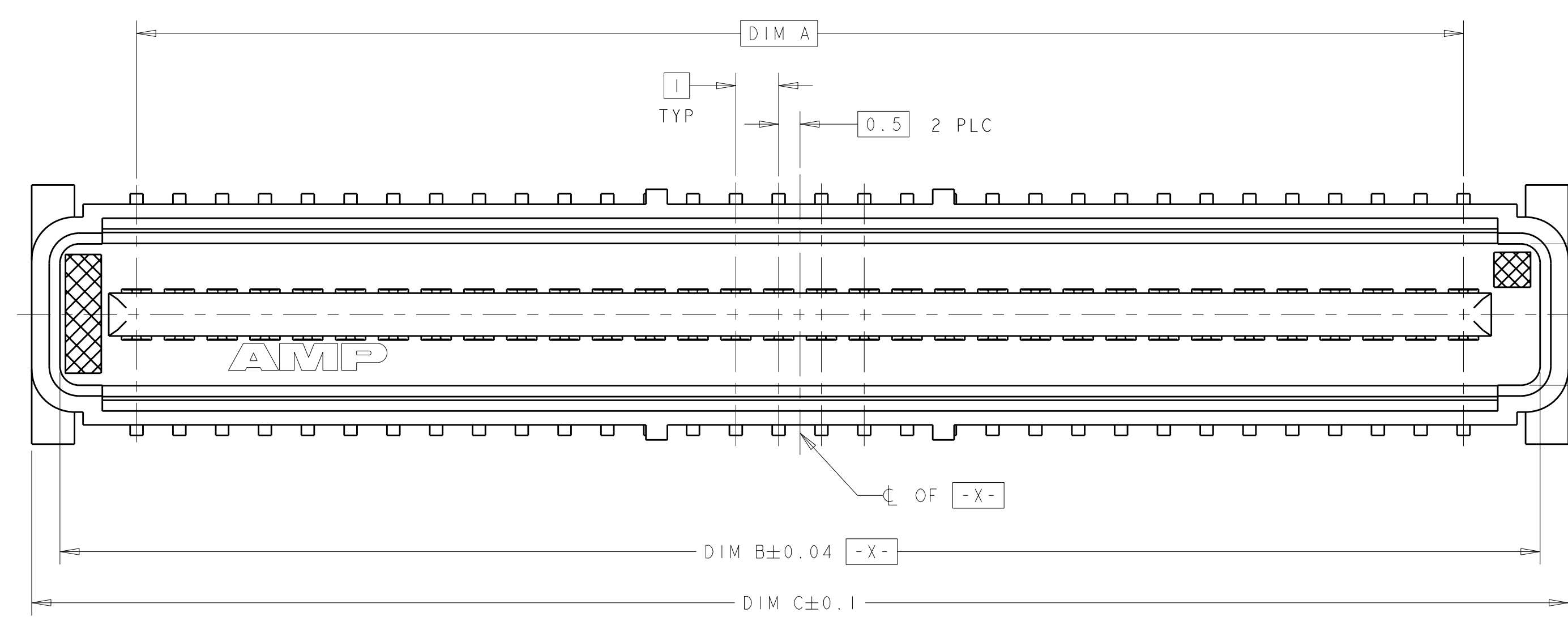
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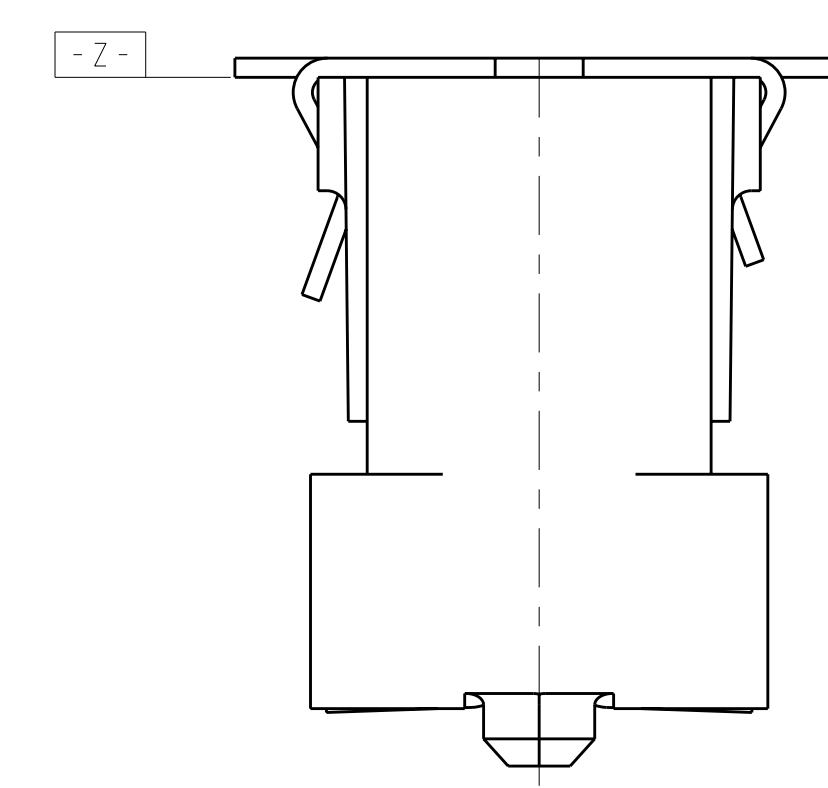
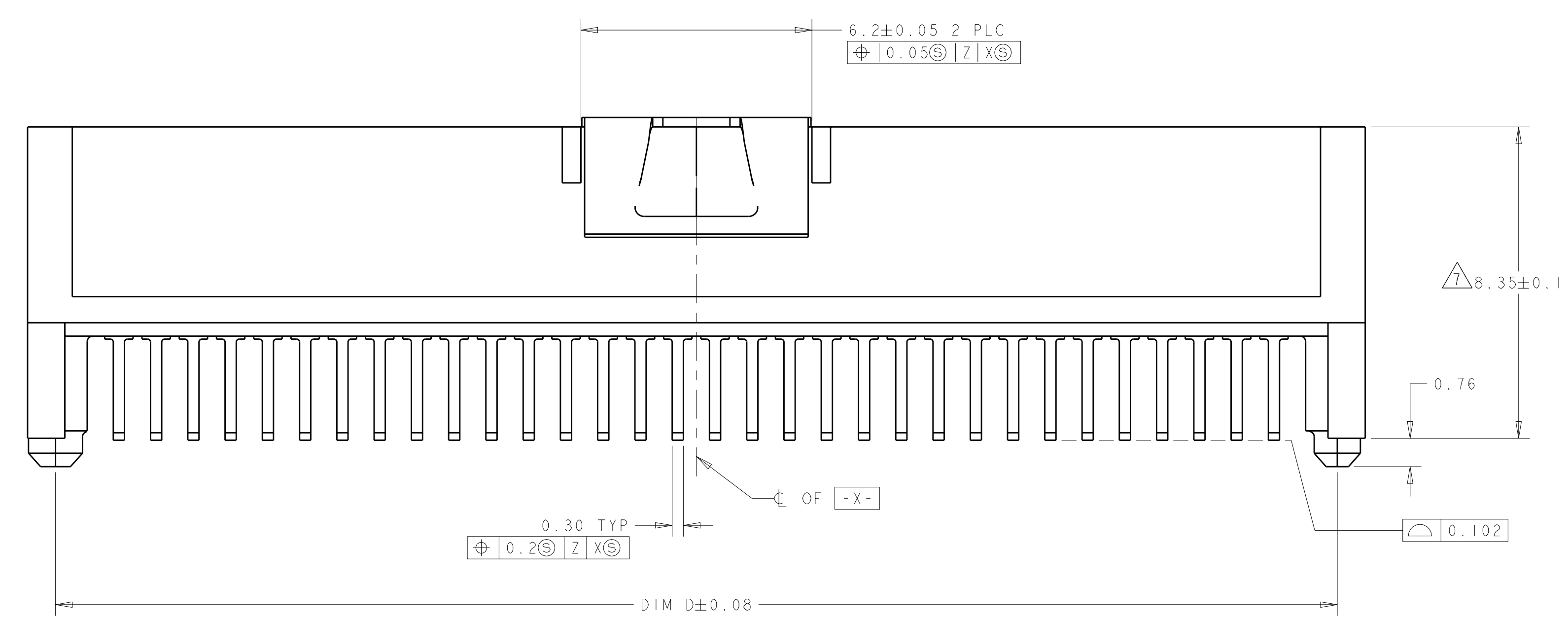


LOC	DIST	REV	DATE	BY	CHK	APPV
AD	00	B2	11MAR2011	RK	HMR	

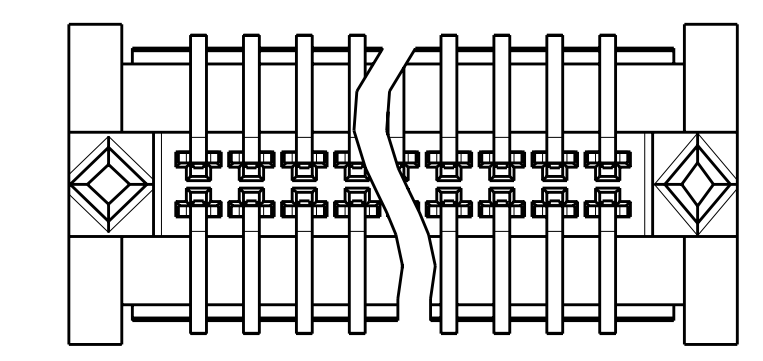


VACUUM COVER

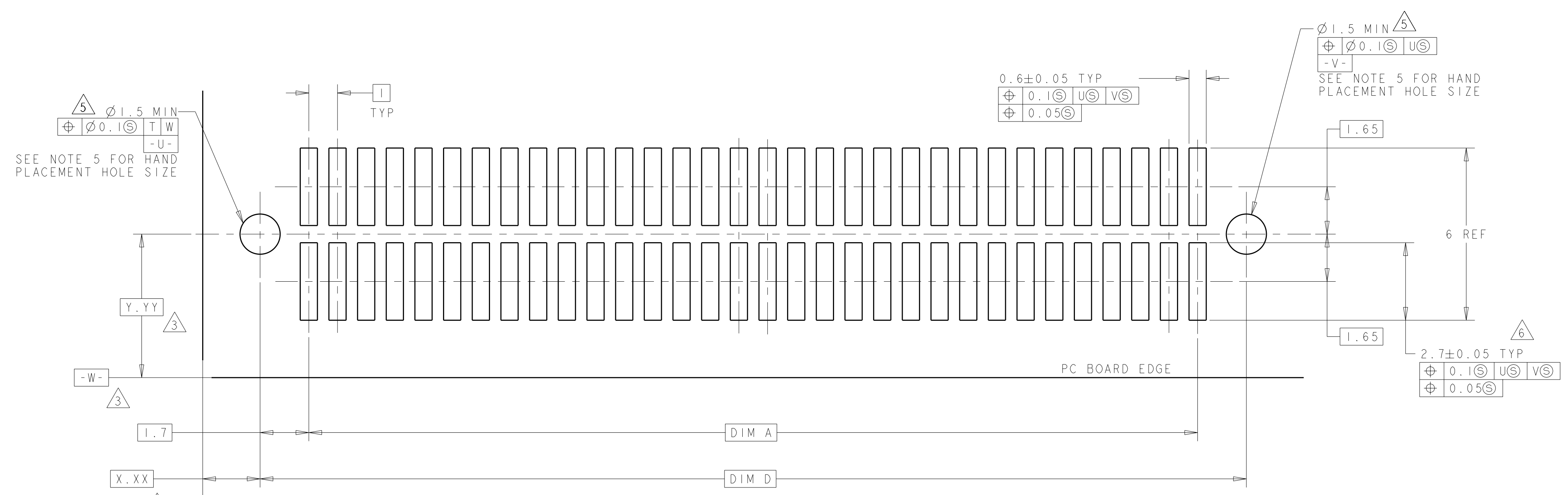
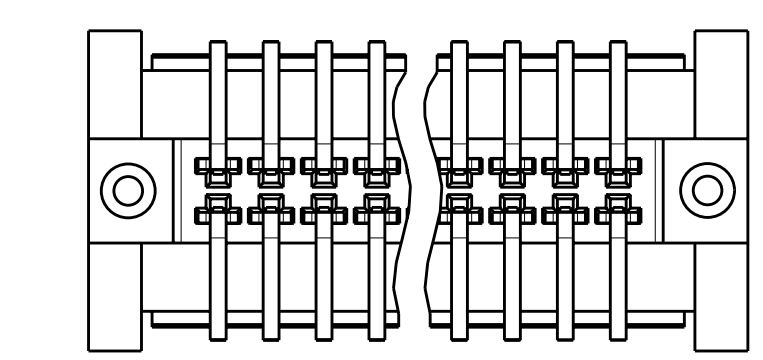
- 1 HOUSING MATERIAL: LIQUID CRYSTAL POLYMER COLOR: BLACK. CONTACT MATERIAL: PHOSPHOR BRONZE.
- 2 CONTACT FINISH: NICKEL UNDERPLATE ALL OVER. MATING SURFACES PLATED TO MEET PLI PERFORMANCE REQUIREMENTS OF INDUSTRY SPECIFICATION EIA-700AAAB, SOLDER TAILS PLATED TIN.
- 3 DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE CUSTOMER. CONSULT AMP ENGINEERING WHEN PLACING MULTIPLE CONNECTORS ON A PC BOARD.
- 4 PACKAGED IN TAPE ON REELS PER EIA-841.
- 5 1.4±0.05 DIAMETER HOLE WHEN PLACING BY HAND.
- 6 SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAB, HOWEVER 2.7 LENGTH ASSURES OPTIMUM SOLDER FILLET.
- 7 REFERRED TO AS DIM N IN EIA 700AAAB SPECIFICATION.
- 8 VACUUM COVER NOT SHOWN IN SOME VIEWS FOR CLARITY.
- 9 5.5 MIN DIAMETER TARGET AREA FOR VACUUM PIP-UP.
- 10 CONTACT FINISH: 0.00381 MINIMUM MATTE TIN PER ASTM B 545 ON SOLDER AREA; 0.00127 MINIMUM GOLD PER ASTM B 488 ON MATING AREA BOTH OVER 0.00127 MINIMUM NICKEL PER SAE-AMS-QQ-N-290 ON ENTIRE CONTACT.
- 11 SQUARE AND DIAMOND SHAPED POSTS
- 12 ROUND SHAPED POSTS



STYLE A POSTS



STYLE B POSTS



RECOMMENDED PC BOARD LAYOUT

POST STYLE	FINISH	DIM D	DIM C	DIM B	DIM A	STACK HEIGHTS	POS	PART NUMBER
12	9	44.4	45.9	44.58	41	10, 12, 13, 15	84	3-5146888-2
12	9	34.4	35.9	34.58	31	10, 12, 13, 15	64	3-5146888-1
12	2	44.4	45.9	44.58	41	10, 12, 13, 15	84	2-5146888-2
12	2	34.4	35.9	34.58	31	10, 12, 13, 15	64	2-5146888-1
11	9	44.4	45.9	44.58	41	10, 12, 13, 15	84	1-5146888-2
11	2	34.4	35.9	34.58	31	10, 12, 13, 15	64	1-5146888-1
11	9	44.4	45.9	44.58	41	10, 12, 13, 15	84	5146888-2
11	2	34.4	35.9	34.58	31	10, 12, 13, 15	64	5146888-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

AWN: B. CARBO 30SEP04  
 CHK: R. WERTZ 30SEP04  
 APPV: R. WERTZ 30SEP04

TE Connectivity

PRODUCT SPEC: 502-1079  
 APPLICATION SPEC: 114-25045

NAME: PLUG ASSEMBLY, W/VACUUM COVER, 1.0mm FH(IEEE 1386) CONNECTOR

SIZE: 114-25045  
 WEIGHT: -  
 CUSTOMER DRAWING

SCALE: 10:1 SHEET 1 OF 1 REV: B2